

FIG. 1

# Cytonix Coat Process

## Equipment - SVG 90 Series Track

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### Cytonix FLW. (Coat and Bake)

Step	Operation	Time (sec)	Speed (rpm)	Accel. (rpm/s)	Exhaust
1	SPIN	3.0	2400	5000	20
2	DISP - 2	2.0	2400	5000	20
3	SPIN	30.0	2400	6000	20
4	SPIN	1.0	600	5000	50
5	BEBR1	8.0	600	5000	50
6	TEBR	6.0	1600	5000	50
7	SPIN	10.0	2000	5000	50
8	END				

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### High Temperature Bake - 180C

Step	Time (sec)	X Pos (mm)
1	100.0	10.0
2	200	6
3	300	4
4	300	0

FIG. 2

## ***MASK 2 - 96/384 Pad Mask***

### ***Critical Operating Parameters***

**Equipment - MTI FlexiFab (serial # 62-E1-2453)**

**Coat recipe**

STEP	TIME	SPEED	ACCEL
1	002.0	00000	05
2	002.0	01200	05
3	000.3	01200	05
4	20.0	2000*	05
5	005.0	01000	05
6	010.0	02000	05
7	010.0	01300	05

*(\*Target RPM for desired thickness)*

### **Positive Resist Process**

Photoresist: Shipley 1811 or 1822

Target thickness - 2.0um +/- .2um

Soft-Bake: 60" @ 105°C

Expose 96/384 Pad @ 350mj/cm<sup>2</sup>

Post Exposure Bake: 60" @ 115°C

**Soft-bake - Hotplate Recipe**

STEP	TIME	TEMP	HEIGHT
1	001.0	105°	0.025
2	060.0	105°	0.000

**PEB - Hotplate Recipe**

STEP	TIME	TEMP	HEIGHT
1	001.0	115°	0.025
2	060.0	115°	0.000

### **Positive Develop Process**

Developer: Shipley MIF 701

Develop Time: 60"

Rinse/Dry

FIG. 3

### Cross Section of Cytonix Chip: Pad Area Etched to Oxide

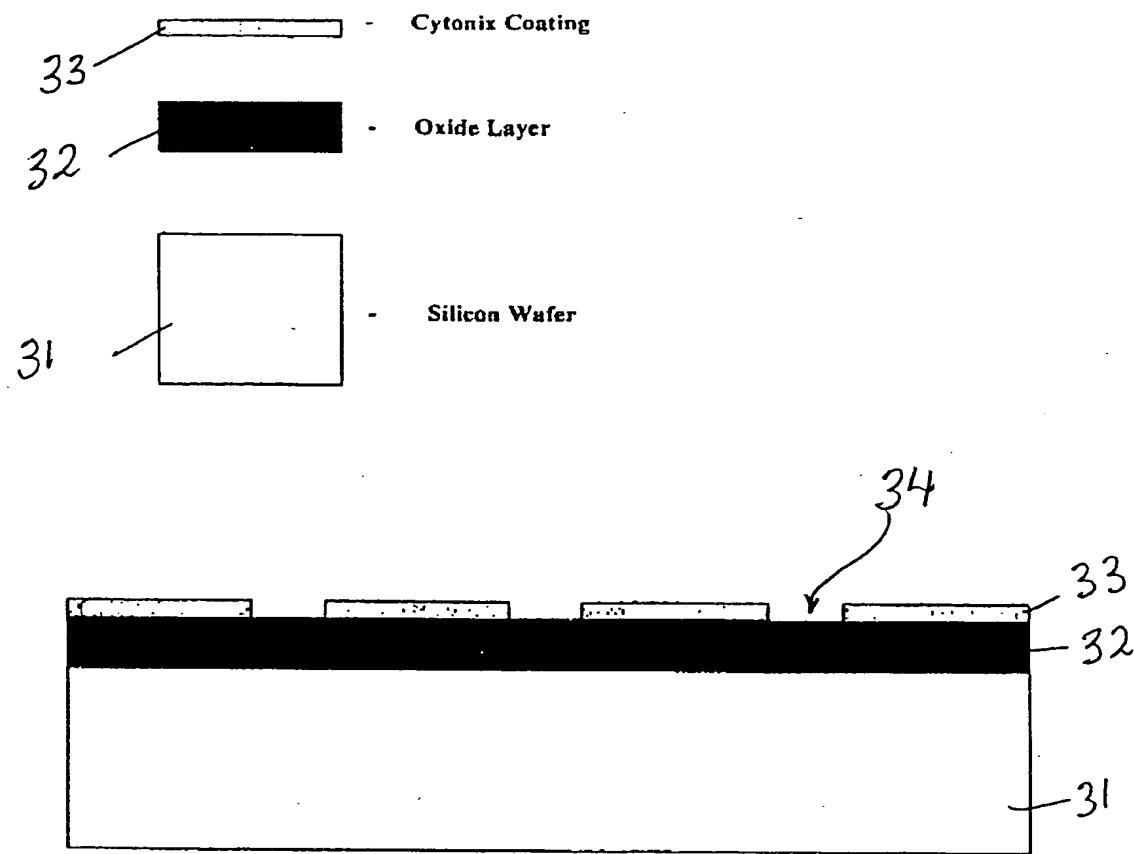


FIG. 4